



SPECIFICATION FOR HCMOS VCXO MtronPTI P/N: M3006S002

Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		49.152000		MHz	
		Fre	quency Sta	bility		
Frequency Stability		-50		+50	ppm	Including calibration tolerance at +25C with Vc = 1.65 and deviation over operating temperature range.
		•	RF Output			
Output Type			MOS Compa			
Output Load			<u>15 pF HCMO</u>	S		
Symmetry (duty cycle)	T _{DC}	45		55	%	@ 50% V _{DD} with HCMOS load
Logic Level "1"		90% V _{DD}			V	
Logic Level "0"				10% V _{DD}	V	
Rise/Fall Time	T _R /T _F			5	ns	From 20% to 80% V _{DD}
Start-Up Time			4	10	ms	
Tristate Function		80% V _{DD} or N/C			V	Pad 5: Outputs enabled
				20% V _{DD}	V	Pad 5: Output disabled
		Freq	uency Adjus	stment		
Pullability		±100			ppm	Referenced to frequency with $Vc = 1.65$
Control Voltage		0.30	1.65	3.00	V	Pad 1
Linearity				10	%	
Modulation Bandwidth	fm	10			kHz	-3 dB
Input Impedance	Zin	1			MΩ	Pad 1
		Supply	/ Voltage &	Current		
Operating Voltage	Vdd	3.13	3.30	3.47	V	
Operating Current	IDD			25	mA	
		Ot	ther Paramet	ters		
			-70			@ 10 Hz
			-100			@ 100 Hz
Phase Noise			-135		dBc/Hz	@ 1 kHz
			-155			@ 10 kHz
			-155			@ 100 kHz

Environmental & Packaging Requirements:

TA	-40		+85	°C	
TS -55 +125 °C					
Per MIL-STD-202, Method 213, Condition C (100		0 g's, 6 ms d	uration, ½ sinewave)		
Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)					
Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium)					
Per EIAJ-STD-002					
See solder profile, Figure 1.					
5 X 7 mm 6-pad leadless ceramic. RoHS compliant.					
	T _A TS Per MII Per MII Per MII Per EI See so	TS -55 Per MIL-STD-202, M Per MIL-STD-202, M Per MIL-STD-883, M Per MIL-STD-202, M Per EIAJ-STD-002 See solder profile, F	T _A -40 TS -55 Per MIL-STD-202, Method 213, Col Per MIL-STD-202, Method 201 & 20 Per MIL-STD-202, Method 1010, B Per MIL-STD-202, Method 112 (1 x Per EIAJ-STD-002 See solder profile, Figure 1.	T _A -40 +85 TS -55 +125 Per MIL-STD-202, Method 213, Condition C (10 Per MIL-STD-202, Method 201 & 204 (10 g's from the second se	T _A -40 +85 °C TS -55 +125 °C Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms di °C °C Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 H °C °C Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. °C °C Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium) °C °C Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium) °C °C See solder profile, Figure 1. °C °C °C





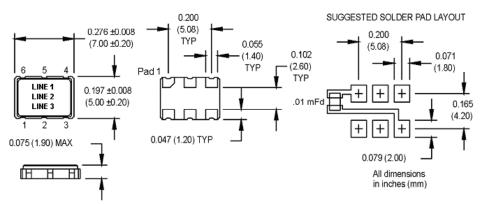
SPECIFICATION FOR HCMOS VCXO MtronPTI P/N: M3006S002

Marking, Pin Out & Dimensions:

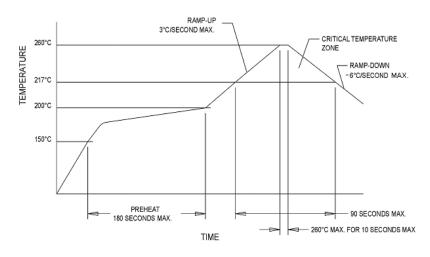
Pad	Function
1	Control Voltage
2	No Connection
3	Ground
4	Output
5	Tristate Control
6	+V _{DD}

Part Marking		
Line 1	M3006S302	
Line 2	49M1520	
Line 3	M yy ww vv	

Legend					
уу	Year				
ww	Work week				
vv	Factory code				



Soldering Conditions:





DATA SHEET REVISION TABLE:

Date	Rev.	Author	Details of Revision
07/22/16	0	MM	Original release